

Product Change Notice PCN99002

A change in the wafer fabrication process used to fabricate the XC4000XL commercial (C-grade and I-grade) product family

Subject: Product Change Notification (PCN99002). “A change in the wafer fabrication process used to fabricate the XC4000XL commercial (C-grade and I-grade) product family.”

Note that this notice does not affect any SMD (Standard Military Drawing) devices.

Products Affected: All commercial (C-grade and I-grade) members of the XC4000XL product line.

Change Description: The XC4000XL product family is currently manufactured in the 0.35 μ M TLM CMOS process at UMC. Seiko will also be utilized to fabricate these products, but in a hybrid *0.25 μ M PLM CMOS process. The Seiko offerings will be form, fit and functionally equivalent to the current product.

* Seiko fabrication process utilizes an "as-drawn" 0.35 μ M transistor structure, but interconnect metallization is drawn in compliance with the 0.25 μ M design rules.

Reason For Change: This change is being made to establish a second source for the XC4000XL product line to ensure continuity of supply. [Qualification Data](#) on XC4000XL product fabricated in this process is attached.

Key Dates: Xilinx will begin shipping XC4000XL product fabricated with the Seiko process on 24 August 1999. Product fabricated in this process can be identified by the wafer fabrication code "K" and the geometry code "P" marked on the product.

Response: No response to this notification is required. Requests for additional data or support should be made within 90 days of notification. Please address any questions you may have via e-mail at "pcn@xilinx.com", or directly by fax at 408 559 1368.